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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Bruno GHYSELEN et al.

Confirmation No.: 7326

Application No.: 10/614,327

Group Art Unit: 2822

Filing Date: July 8, 2003

Examiner: Wilczewski, Mary A.

For: TRANSFER OF A THIN LAYER FROM A  
WAFER COMPRISING A BUFFER LAYER

Attorney Docket No.: 4717-7600

**RESPONSE TO RESTRICTION REQUIREMENT**

**Non-Fee Response**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Examiner's Action mailed June 30, 2004, Applicants hereby elect Group I, Claims 1-25 and 34-35 drawn to a method of preparing a semiconductor wafer.

Applicants expressly reserve the right to file one or more divisional or continuing applications to protect the inventions of the non-elected group and other disclosed, but unclaimed, subject matter prior to the issuance of this application.

No fee is believed to be due for this response. Should any fees be required, please charge such fees to Winston & Strawn LLP Deposit Account No. 50-1814.

Respectfully submitted,

July 22, 2004  
Date

E. Bradley Gould (Reg. No. 41,792)  
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